

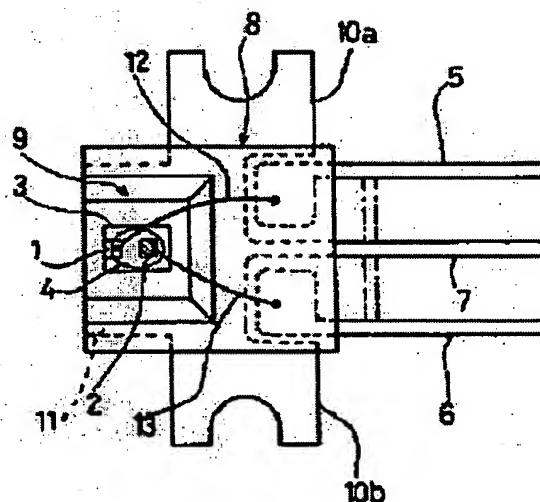
SEMICONDUCTOR LASER DEVICE

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Classification:
- **International:** H01S3/18
- **European:**
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Abstract of JP6204604

PURPOSE: To make a semiconductor laser device advantageous on thinning and a manufacturing cost side in consideration of electrical structure and a heat-dissipating effect while improving the efficiency of manufacture.

CONSTITUTION: A recessed section 9, in which a semiconductor laser chip 1 and a photo-detector 2 are arranged, is formed into a package 8, and a clearance between an outgoing port at the rear of the semiconductor laser chip 1 and the photo-detector 2 in the recessed section 9 is buried with a transparent material 4 while the specified section of the sidewall of the recessed section 9 is removed. Projecting pieces 10a, 10b for installation are projected from the side surface of the package 8 while a pedestal 11, on which a substrate 3, on which the semiconductor laser chip 1 is mounted, is set up, is formed as the projecting pieces 10a, 10b and lead terminals 7 for grounding are connected integrally.



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